L Number	Hits	Search Text	DB	Time stamp
3	14	((conductive near3 wire) (bond adj3 wire)) same ((resona$4 near3 frequenc$3) (different near3 length) (different near3 thickness)) and (car automobile vehicle)	USPAT	2004/10/14 08:20
4	390	semiconductor near3 package and (car automobile vehicle in-vehicle in?vehicule)	USPAT	2004/10/14 08:19
7	1	(semiconductor near3 package and (car automobile vehicle in-vehicle in?vehicule)) and ((conductive near3 wire) (bond adj3 wire)) and ((resona$4 near3 frequenc$3) (different near3 length) (different near3 thickness))	USPAT	2004/10/14 08:20
-	163	((conductor wire) with (resona$5 near3 frequenc$3)) same substrate	USPAT	2004/10/13 21:26
-	3	(((conductor wire) with (resona$5 near3 frequenc$3)) same substrate) and (electrode adj3 pad)	USPAT	2004/10/06 20:54
-	11	((conductor wire) with (resona$5 near3 frequenc$3)) same substrate same (pattern$3 near3 conductor)	USPAT	2004/10/06 21:10
-	20	(bond adj3 wire) same ((resona$4 near3 frequenc$3) (different near3 length))	USPAT	2004/10/14 08:01
-	4	(parallel near3 (bond adj2 wire)) same substrate	USPAT	2004/10/06 21:46
-	17	(parallel near3 (bond adj2 wire))	USPAT	2004/10/06 21:54
-	31	((multi multiple parallel) near3 (bond adj2 wire))	USPAT	2004/10/06 21:54
-	14	(((multi multiple parallel) near3 (bond adj2 wire))) not ((parallel near3 (bond adj2 wire)))	USPAT	2004/10/13 21:25
-	5374	frequency with "n" adj times	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 21:22
-	8	(frequency with "n" adj times) and ((conductor wire) with (resona$5 near3 frequenc$3))	USPAT	2004/10/13 21:24
-	23	((conductor wire) with (resona$5 near3 frequenc$3)) same substrate and (automobile car vehicle)	USPAT	2004/10/13 21:27

L Number	Hits	Search Text	DB	Time stamp
-	1	10/615680	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 14:25
-	1	10/615680	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:38
-	24799	acoustic near3 device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:39
-	3183	acoustic near3 wave near3 resonator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:40
-	373	electrode near pad and (connect$3 near3 conductor) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:23
-	4	(acoustic near3 wave near3 resonator) and (electrode near pad and (connect$3 near3 conductor) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:42
-	2169	(acoustic near3 wave near3 resonator) and frequency	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:54
-	4	((acoustic near3 wave near3 resonator) and frequency) and (electrode near pad and (connect$3 near3 conductor) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:42
-	17	(electrode near pad and (connect$3 near3 conductor) with substrate) and acoustic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 18:11
-	30	(acoustic near3 wave near3 resonator) and wire near5 frequency	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 17:55
-	29	((acoustic near3 wave near3 resonator) and wire near5 frequency) not ((electrode near pad and (connect$3 near3 conductor) with substrate) and acoustic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 18:10
-	996	(310/313,348).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 18:10

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-	3820	(333/32,187,193).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 18:11
-	6191	(257/100,684,778,787).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/01 18:12
-	284	((wire conductor bus line) near3 (size length width characteristic)) with (frequency near3 response)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:06
-	0	(((wire conductor bus line) near3 (size length width characteristic)) with (frequency near3 response)) and substrate and (electrode near4 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:43
-	21	(((wire conductor bus line) near3 (size length width characteristic)) with (frequency near3 response)) and substrate and (electrode adn pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:43
-	14	(((wire conductor bus line) near3 (size length width characteristic)) with (frequency near3 response)) and substrate and (electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:43
-	53	((wire conductor bus) near3 (size length width characteristic)) with (frequency near3 response)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:01
-	32	(((wire conductor bus) near3 (size length width characteristic)) with (frequency near3 response)) not antenna	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:52
-	0	((((wire conductor bus) near3 (size length width characteristic)) with (frequency near3 response)) not antenna) and electrode and subtrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:54
-	4	((((wire conductor bus) near3 (size length width characteristic)) with (frequency near3 response)) not antenna) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:52
-	0	(((wire conductor bus) near3 (size length width characteristic)) with (frequency near3 response)) and electrode and subtrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:54
-	6	(((wire conductor bus) near3 (size length width characteristic)) with (frequency near3 response)) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:54

-	10925	substrate and (electrode near3 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:02
-	16122	substrate and (electrode near3 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:02
-	14	(((wire conductor bus line) near3 (size length width characteristic)) with (frequency near3 response)) and conductor near3 pattern$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:08
-	6	((((wire conductor bus line) near3 (size length width characteristic)) with (frequency near3 response)) and conductor near3 pattern$3) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:08
-	373	electrode near pad and (connect$3 near3 conductor) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:10
-	3504	((wire conductor bus) near3 (size length width characteristic)) with different	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:11
-	3504	((wire conductor bus) near3 ((size length width characteristic)) with different)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:38
-	4	(electrode near pad and (connect$3 near3 conductor) with substrate) and (((wire conductor bus) near3 ((size length width characteristic)) with different))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:13
-	19	(substrate and (electrode near3 pad)) and (((wire conductor bus) near3 ((size length width characteristic)) with different))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:19
-	4386	(conductor near3 pattern) near5 substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:21
-	594	(device near3 electrode near3 pad) near5 device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:20
-	1052	(device near3 electrode near3 pad) near5 device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:20

-	6003	(conductor near3 pattern) near5 substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:21
-	19	((device near3 electrode near3 pad) near5 device) and ((conductor near3 pattern) near5 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:34
-	1	(((wire conductor bus) near3 ((size length width characteristic)) with different)) and ((device near3 electrode near3 pad) near5 device) and ((conductor near3 pattern) near5 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:34
-	24	(((wire conductor bus) near3 ((size length width characteristic)) with different)) and ((conductor near3 pattern) near5 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:10
-	2	wire adj thin adj lines with connect$3 with pattern with substrate and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:14
-	2	differ$3 with frequencies and wire adj thin with lines	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:52
-	543	device near3 electrode and ((connect$3 near3 conductor) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:53
-	899	device near3 electrode and ((connect$3 near3 conductor) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:24
-	104	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and plurality near3 wir$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:18
-	12	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((plurality near3 wir$3) with different)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:55
-	12	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((plurality near3 wir$3) with different$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:57
-	3	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((plurality near3 wir$3) near3 different$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 16:55

-	204	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((wire conductor bus) near3 (size length width characteristic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:18
-	12	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((wire conductor bus) near3 (size length width characteristic)) with different$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:46
-	10	((device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((wire conductor bus) near3 (size length width characteristic)) with different$3) not ((device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((plurality near3 wir$3) with different))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:03
-	10	((device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((wire conductor bus) near3 (size length width characteristic)) with different$3) not ((device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((plurality near3 wir$3) with different$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:03
-	32	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and ((wire conductor bus) with different$3 near5 (size length width characteristic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:14
-	1	(device near3 electrode and ((connect$3 near3 conductor) with substrate)) and wire with different near3 (size length width characteristic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:21
-	5615	wire with different near3 (size length width characteristic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:22
-	1	(wire with different near3 (size length width characteristic)) and (device near3 electrode and ((connect$3 near3 conductor) with substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:23
-	1	(wire with different near3 (size length width characteristic)) and electrode near pad and (connect$3 near3 conductor) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:23
-	1	(wire with different near3 (size length width characteristic)) and device near3 electrode and ((connect$3 near3 conductor) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:28
-	81	connect$3 near3 path with electrode near3 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:29
-	3	(connect$3 near3 path with electrode near3 pad) and (connect$3 near3 wir$4) near5 different	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:31

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-	39	(connect$3 near3 path with electrode near3 pad) and connect$3 near3 wir$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:44
-	326	(electronic near3 device near3 carr$4) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:45
-	2	((electronic near3 device near3 carr$4) with substrate) and ((wire conductor bus) near3 (size length width characteristic)) with different$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:57
-	16	((electronic near3 device near3 carr$4) with substrate) and ((wire conductor bus) near3 (size length width characteristic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:47
-	1	((electronic near3 device near3 carr$4) with substrate) and wire with different near3 (size length width characteristic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:50
-	6	inoue-hisayuki.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:53
-	62	board and connect$3 with mechanical$3 near3 vibration and pack$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:55
-	6	mother near3 board and connect$3 with mechanical$3 near3 vibration and pack$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:55
-	16	(board and connect$3 with mechanical$3 near3 vibration and pack$3) and ((wire conductor bus) near3 (size length width characteristic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 17:58
-	1586	(361/776-779).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:46
-	266	((361/776-779).CCLS.) and frequencies	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:47
-	266	((361/776-779).CCLS.) and frequenc$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:15

-	174	(((361/776-779).CCLS.) and frequenc$3) and substrate and (IC die component device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:15
-	19	(("6414386") or ("6057601") or ("6031283") or ("5796589") or ("5530287") or ("5235209") or ("6448639") or ("6137168") or ("6790710")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:29
-	488	(29/842).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:13
-	9428	(257/690,691,692,700,784,787).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:15
-	1271	((257/690,691,692,700,784,787).CCLS.) and frequenc$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:15
-	74	((29/842).CCLS.) and frequenc$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:15
-	949	(((257/690,691,692,700,784,787).CCLS.) and frequenc$3) and substrate and (IC die component device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:15
-	42	(((29/842).CCLS.) and frequenc$3) and substrate and (IC die component device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:16
-	40	((((257/690,691,692,700,784,787).CCLS.) and frequenc$3) and substrate and (IC die component device)) and wire near5 different	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:23
-	909	((((257/690,691,692,700,784,787).CCLS.) and frequenc$3) and substrate and (IC die component device)) not (((((257/690,691,692,700,784,787).CCLS.) and frequenc$3) and substrate and (IC die component device)) and wire near5 different)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:20
-	88	((((257/690,691,692,700,784,787).CCLS.) and frequenc$3) and substrate and (IC die component device)) and plurality near3 bond$3 near3 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:25
-	2	("6008532").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:32

-	2547	(((integrated adj circuit) IC) near3 device) with connect$ near4 (wir$4 bond$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:36
-	295	(((integrated adj circuit) IC) near3 device) with connect$ near4 (wir$4 bond$3) and ((printed adj circuit adj board) PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:37
-	35	(((integrated adj circuit) IC) near3 device) with connect$ near4 (wir$4 bond$3) with ((printed adj circuit adj board) PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:45
-	21	(((integrated adj circuit) IC) near3 device) with connect$ near4 (wir$4 bond$3 adj wir$4) with ((printed adj circuit adj board) PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:46